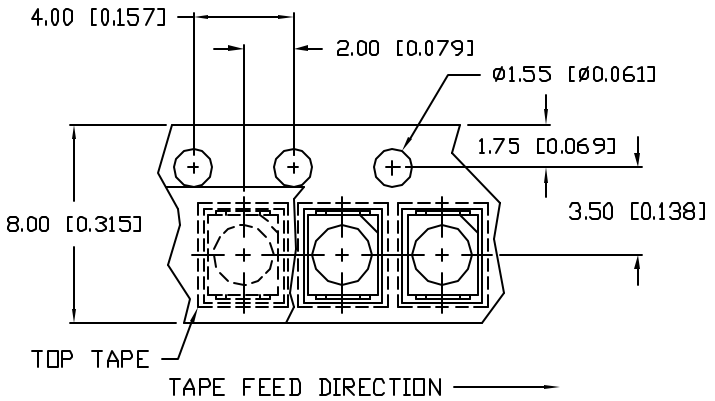
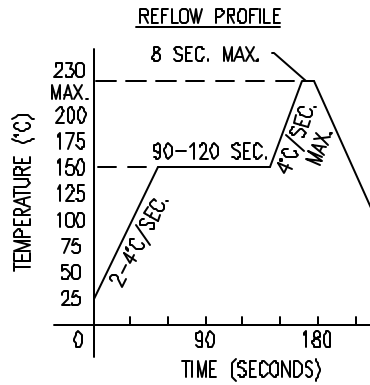
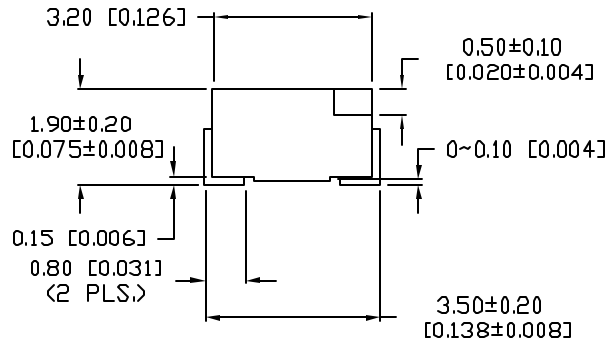
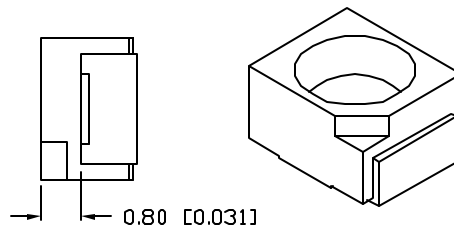
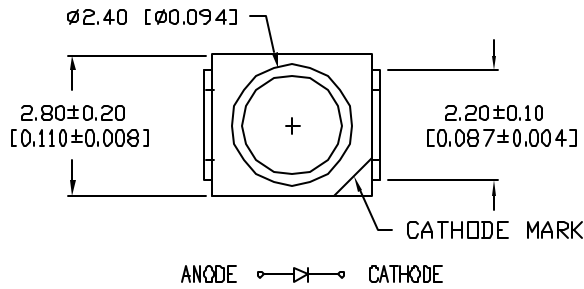
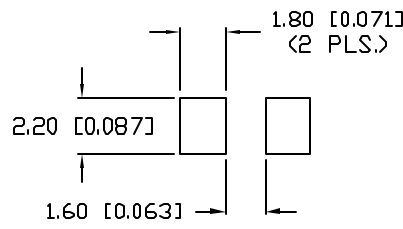


UNCONTROLLED DOCUMENT



RECOMMENDED SOLDER PAD LAYOUT



PART NUMBER		REV.
SML-LX2832USBC-TR		A
REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #10967.	3.14.03

ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		470		nm	
FORWARD VOLTAGE		3.5	4.0	V_f	
REVERSE VOLTAGE	5.0			V_r	$I_f=100\mu\text{A}$
AXIAL INTENSITY		60		mcd	$I_f=20\text{mA}$
VIEWING ANGLE		120		2x theta	
EMITTED COLOR:	BLUE				
EPOXY LENS FINISH:	WATER CLEAR				

LIMITS OF SAFE OPERATION AT 25°C

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	160	mA
STEADY CURRENT	30	mA
POWER DISSIPATION	100	mW
DERATE FROM 25°C	-1.2	mW/°C
OPERATING TEMP.	-30 TO +85	°C
STORAGE TEMP.	-40 TO +85	°C

* $t < 10\mu\text{s}$

NOTES:

- THE POLARITY MARK IS ORIENTED TOWARDS THE TAPE SPROCKET HOLE.

CAUTION: STATIC SENSITIVE DEVICE
FOLLOW PROPER E.S.D. HANDLING PROCEDURES
WHEN WORKING WITH THIS PART.

CAUTION: MOISTURE SENSITIVE DEVICE
PER JEDEC LEVEL 4 STANDARDS

UNCONTROLLED DOCUMENT

*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), XX=±0.5 (±0.020), XXX=±0.25 (±0.010), XXXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030), MIN.=^{+DECIMAL PRECISION}-0.00 MAX.=^{+0.00}-DECIMAL PRECISION

REV.	PART NUMBER
A	SML-LX2832USBC-TR

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290 E. HELEN ROAD
PALATINE, IL 60067-6976
PHONE: +1.847.359.2790
US WEB: www.lumex.com
TW WEB: www.lumex.com.tw

2.8mm x 3.2mm SURFACE MOUNT LED WITH REFLECTOR,
470nm ULTRA SUPER BLUE LED, WATER CLEAR LENS,
2,000 PER TAPE AND REEL.

RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY:	CHECKED BY:	APPROVED BY:	DATE: 1.11.01
BC			PAGE: 1 OF 1
			SCALE: N/A